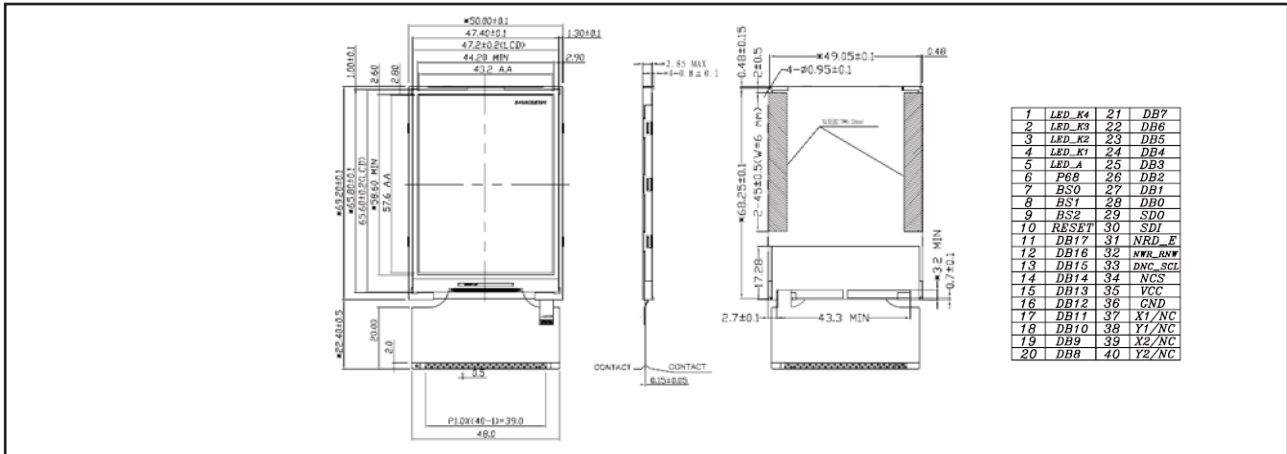


TFT TRANSMISSIVE LCD MODULES

YTS 280DLAC-03-200N

2.8", 240 X 320 DOTS, 1/320 DUTY

EXTERNAL DIMENSION AND DISPLAY PATTERN



MECHANICAL DATA

ITEM	SPECIFICATION	UNIT
Module Size (W x H)	50.0 x 69.20 x 2.85	mm
Active Area (W x H)	44.20 x 58.60	mm
Viewing Direction	6:00	o'clock
Number of Dots	240 (RGB) x 320	dots
Colors	262K	
Surface Brightness	160	cd/m ²

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Supply Voltage 1	IOV _{CC}	-0.3	4.6	V
Supply Voltage 2	V _{Cl}	-0.3	4.6	V
Supply Voltage 3	DDV _{DH}	-0.3	9.0	V
Supply Voltage 4	V _{CL}	-4.6	0.3	V
Supply Voltage 5	V _{GH}	-0.3	18.5	V
Supply Voltage 6	V _{GL}	-18.5	0.3	V
Input Voltage	V _{IN}	-0.3	V _{Cl} +0.3	V
Operating Temperature		See page 8		
Storage Temperature				

PIN CONFIGURATION

PIN	SYMBOL	SIGNAL DESCRIPTION
1	LED_K4	Backlight LED Power
2	LED_K3	
3	LED_K2	
4	LED_K1	
5	LED_A	
6	P68	Select the MPU Interface Mode
7	BS0	Select the MPU Interface Mode
8	BS1	Select the MPU Interface Mode
9	BS2	Select the MPU Interface Mode
10	RESET	Reset Pin
11-28	DB17-DB0	Data Bus
29	SD0	Serial Data Output. If not use, let it to open.
30	SD1	Serial Data Input Pin
31	NRD_E	180 System: Serves as a Read Signal and Read Data at the Low Level. M68 System: 0 - Read/Write Disable; 1 - Read/Write Enable. Fix it to IOV _{CC} or V _{SSD} Level when Using Serial Buss Interface.
32	NWR_RNW	180 System: Serves as a Write Signal and Write Data at the Rising Edge. M68 System: 0 - Write; 1 - Read. Fix it to IOV _{CC} or V _{SSD} Level when Using Serial Buss Interface.
33	DNC_SCL	The Signal for Command or Parameter Select under Parallel Mode
34	NCS	Chip Select Signal
35	VCC	Power Supply
36	GND	Ground
37-40	X1/NC, Y1/NC, X2/NC, Y2/NC	No Connection

ELECTRICAL CHARACTERISTICS, Ta = 25°C

ITEM	SYMBOL	CONDITION	SPEC. VALUE			UNIT
			MIN.	TYP.	MAX.	
TFT Gate ON Voltage	V _{GH}			15.0		V
TFT Gate OFF Voltage	V _{GL}	Ta = +25°C		-8.0		V
TFT Common Electrode Voltage	V _{comH} V _{comL}		2.5 -2.0		4.5 0	V

Note (1): V_{com} must be adjusted to optimize display quality: cross talk, contrast ratio and etc.
 Note (2): V_{GH} is TFT gate operating voltage.
 Note (3): V_{GL} is TFT gate operating voltage. The storage capacitance structure of this products is C_{st} (Storage on Common).
 The low voltage level of V_{GL} signal must be fluctuated with same phase as V_{com}, in case of Storage on Gate structure.
 Note (4): Environmental condition: 25°C ± 5°C.
 Note (5): Operating Voltage V_{CC} = 3.3V

BACKLIGHTING CHARACTERISTICS, Ta = 25°C, LED

ITEM	SYMBOL	CONDITION	SPEC. VALUE			UNIT
			MIN.	TYP.	MAX.	
Supply Voltage	V _{DD} - V _{SS}		3.0		3.4	V
Supply Current	I _{DD}	fixed		60		μA
Luminance	L _v		3000		5000	cd/m ²
Average	Avg		80			%
Colour Coordinate	X		0.26		0.31	
	Y		0.26		0.31	

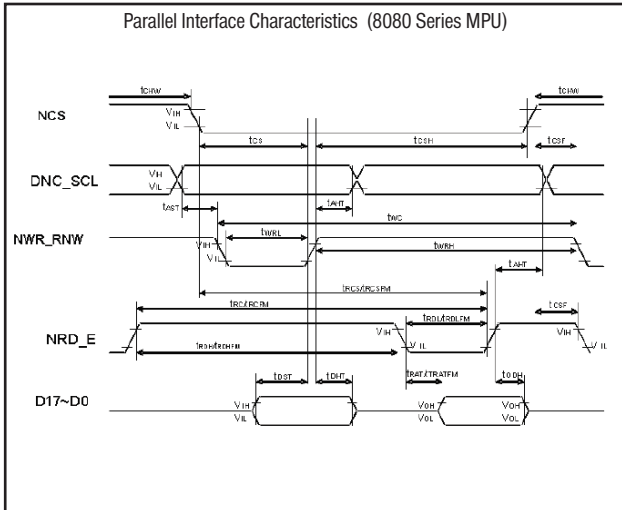
Note (6): Operating temperature -20°C to +70°C; Storage temperature -30°C to +80°C.
 Note (7): LED - 4 pcs.

TFT TRANSMISSIVE LCD MODULES YTS 280DLAC-03-200N

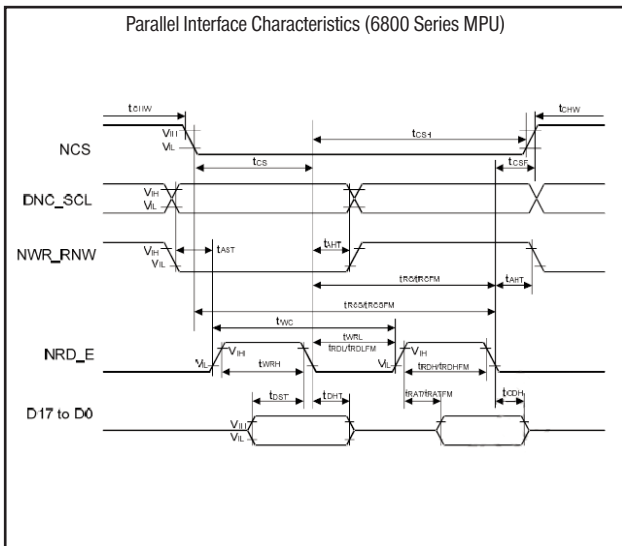
2.8", 240 X 320 DOTS, 1/320 DUTY

INTERFACE TIMING CHARACTERISTICS

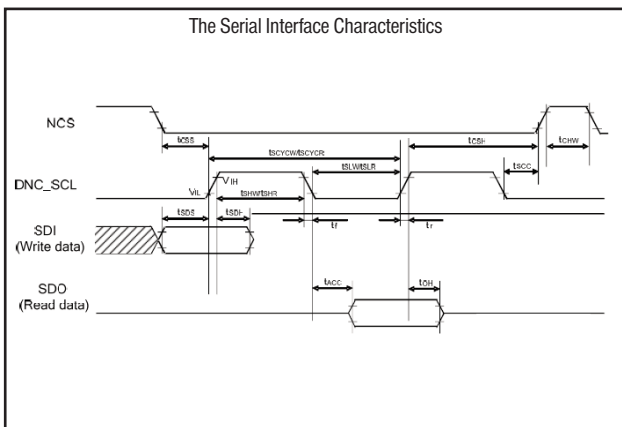
$V_{SSA}=0V, IOCC=1.65V \text{ to } 2.9V, VCI=2.3V \text{ to } 2.9V, T_a=-30^{\circ}C \text{ to } 70^{\circ}C$



Note (1): The input signal rise time and fall time (t_r, t_f) is specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of IOV_{CC} for input signals.



Note (2): The input signal rise time and fall time (t_r, t_f) is specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of IOV_{CC} for input signals.



Note (2): The input signal rise time and fall time (t_r, t_f) is specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of IOV_{CC} for input signals.

PARAMETER	SIGNAL	SYMBOL	TEST CONDITIONS	MIN.	MAX.	UNIT
Address Hold Time	DNC_SCL	t_{AHT}	Write/Read	10		ns
Address Setup Time	DNC_SCL	t_{AST}	Write/Read	10		ns
Chip Select „H“ Pulse Width		t_{CHW}		0		ns
Chip Select Setup Time (Write)		t_{CS}		35		ns
Chip Select Setup Time	NCS	t_{RCSEFM}		355		ns
Chip Select Wait Time (Write/Read)		t_{CSF}		10		ns
Chip Select Hold Time		t_{CSH}		10		ns
Write Cycle		t_{WC}		100		ns
Control Pulse „H“ Duration	NWR_RNW	t_{WRH}		35		ns
Control Pulse „L“ Duration	NWR_RNW	t_{WRL}		35		ns
Read Cycle		t_{RCFM}		450		ns
Control Pulse „H“ Duration	NRD_E	t_{RDHF}	When read from GRAM	90		ns
Control Pulse „L“ Duration	NRD_E	t_{RDLF}	When read from GRAM	355		ns
Data Setup Time	D ₁₇ to D ₀	t_{DST}	for max. $C_L=30$ pF for min. $C_L=8$ pF	15		ns
Data Hold Time	D ₁₇ to D ₀	t_{DHT}	for max. $C_L=30$ pF for min. $C_L=8$ pF	10		ns
Read Access Time	D ₁₇ to D ₀	t_{RATF}	for max. $C_L=30$ pF for min. $C_L=8$ pF		340	ns
Output Disable Time		t_{ODH}		20	80	ns

PARAMETER	SIGNAL	SYMBOL	TEST CONDITIONS	MIN.	MAX.	UNIT
Address Hold Time	DNC_SCL	t_{AHT}	Write/Read	10		ns
Address Setup Time	DNC_SCL	t_{AST}	Write/Read	10		ns
Chip Select „H“ Pulse Width		t_{CHW}		0		ns
Chip Select Setup Time (Write)		t_{CS}		35		ns
Chip Select Setup Time	NCS	t_{RCSEFM}		355		ns
Chip Select Wait Time (Write/Read)		t_{CSF}		10		ns
Chip Select Hold Time		t_{CSH}		10		ns
Write Cycle		t_{WC}		100		ns
Control Pulse „H“ Duration	NWR_RNW	t_{WRH}		35		ns
Control Pulse „L“ Duration	NWR_RNW	t_{WRL}		35		ns
Read Cycle		t_{RCFM}		450		ns
Control Pulse „H“ Duration	NRD_E	t_{RDHF}	When read from GRAM	90		ns
Control Pulse „L“ Duration	NRD_E	t_{RDLF}	When read from GRAM	355		ns
Data Setup Time	D ₁₇ to D ₀	t_{DST}	for max. $C_L=30$ pF for min. $C_L=8$ pF	10		ns
Data Hold Time	D ₁₇ to D ₀	t_{DHT}	for max. $C_L=30$ pF for min. $C_L=8$ pF	10		ns
Read Access Time (ID)	D ₁₇ to D ₀	t_{RAT}	for max. $C_L=30$ pF for min. $C_L=8$ pF		100	ns
Read Access Time (FM)	D ₁₇ to D ₀	t_{RATF}	for max. $C_L=30$ pF for min. $C_L=8$ pF		340	ns
Output Disable Time		t_{ODH}		20	80	ns

PARAMETER	SIGNAL	SYMBOL	TEST CONDITIONS	MIN.	MAX.	UNIT
Serial Clock Cycle (Write)		t_{SCYC}		100		ns
DNC_SCL „H“ Pulse Width (Write)	DNC_SCL	t_{SHW}		35		ns
DNC_SCL „L“ Pulse Width (Write)	DNC_SCL	t_{SLW}		35		ns
Data Setup Time (Write)	SDI	t_{SDS}		30		ns
Data Hold Time (Write)	SDI	t_{SDH}		30		ns
Serial Clock Cycle (Read)		t_{SCYC}		150		ns
DNC_SCL „H“ Pulse Width (Read)	DNC_SCL	t_{SHR}		60		ns
DNC_SCL „L“ Pulse Width (Read)	DNC_SCL	t_{SLR}		60		ns
Access Time		t_{ACC}	SD_0 for max. $C_L=30$ pF for min. $C_L=8$ pF	45	100	ns
Output Disable Time		t_{OH}	for min. $C_L=8$ pF	15	100	ns
DNC_SCL to Chip Select	DNC_SCL, NCS	t_{SCC}		15		ns
NCS „H“ Pulse Width		t_{CHW}		45		ns
Chip Select Setup Time	NCS	t_{CSS}		60		ns
Chip Select Hold Time		t_{CSH}		65		ns